



# PARA LIGHT ELECTRONICS CO., LTD.

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## DATA SHEET

PART NO. : C402I-10

REV : A / 0

CUSTOMER'S APPROVAL : \_\_\_\_\_

DCC : \_\_\_\_\_

DRAWING NO. : DS12180241G

DATE : 20181113

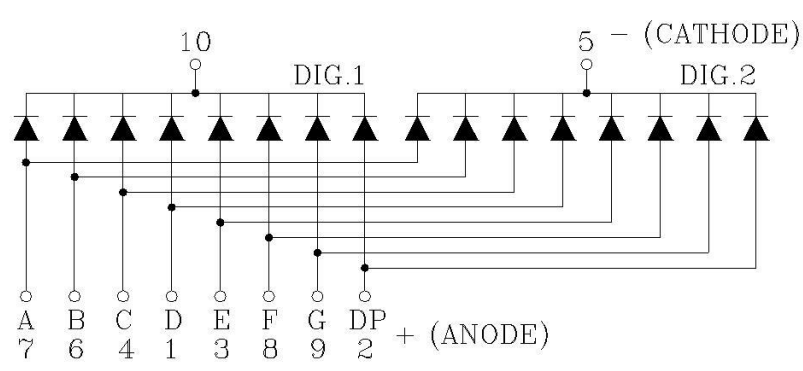
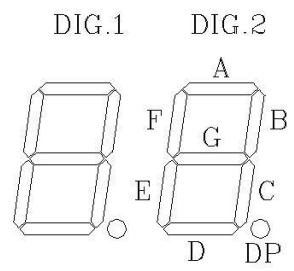
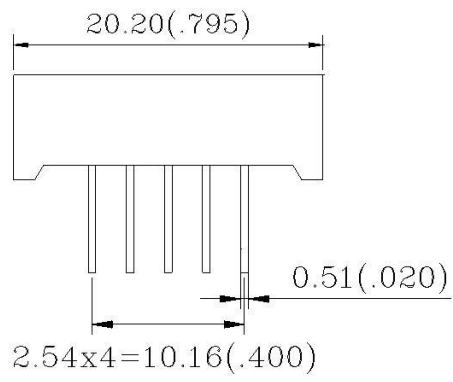
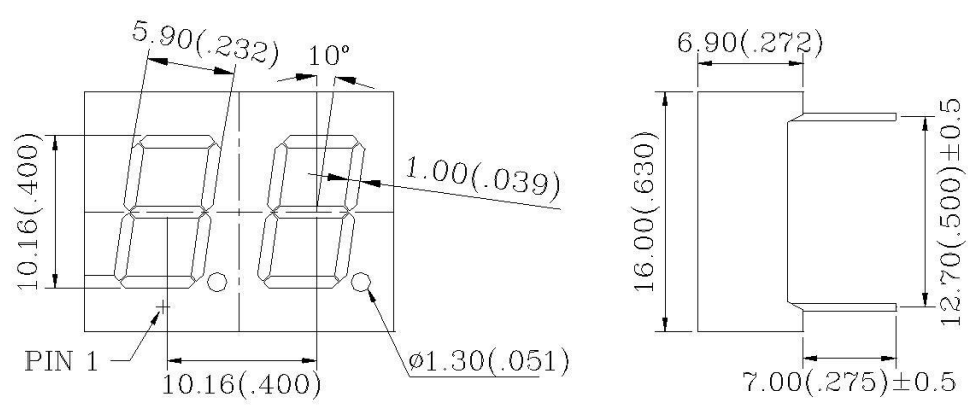
Page : 1



# 0.4 INCH DUAL DIGITS DISPLAY

C402I-10 REV:A/0

## PACKAGE DIMENSIONS



NOTES : 1. All dimensions are in millimeters. (inches)  
2. Tolerance is  $\pm 0.25(0.01)$  unless otherwise specified.



## 0.4 INCH DUAL DIGITS DISPLAY

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## FEATURES

10.16mm (0.4 inch ) DIGIT HEIGHT  
 COMMON CATHODE  
 I.C. COMPATIBLE  
 LOW POWER CONSUMPTION  
 Pb FREE PRODUCTS  
 BLACK FACE, WHITE SEGMENTS

Raw Material : GaAlInP/GaAs

ABSOLUTE MAXIMUM RATING : ( Ta = 25°C )

SYMBOL	PARAMETER	SUPER RED	UNIT
PD	Power Dissipation Per Segment	60	mW
VR	Reverse Voltage Per Segment	5	V
IAF	Continuous Forward Current Per Segment	30	mA
IPF	Peak Forward Current Per Segment (1/10 Duty Cycle,0.1ms Pulse Width)	100	mA
—	Derating Linear From 25°C Per Segment	0.4	mA/°C
Topr	Operating Temperature Range	-35°C to 85°C	
Tstg	Storage Temperature Range	-35°C to 85°C	

ELECTROOPTICAL CHARACTERISTICS : ( Ta = 25°C )

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
VF	Forward Voltage , Per Segment	IF = 20mA		1.8	2.2	V
IR	Reverse Current , Per Segment	VR = 5V			100	A
λP	Peak Emission Wavelength	IF = 20mA		660		nm
λD	Dominant Wavelength	IF = 20mA		640		nm
λ	Spectral Line Half—Width	IF = 20mA		20		nm
IV	Luminous Intensity Per Segment	IF = 10mA	2.4	6.0		mcd

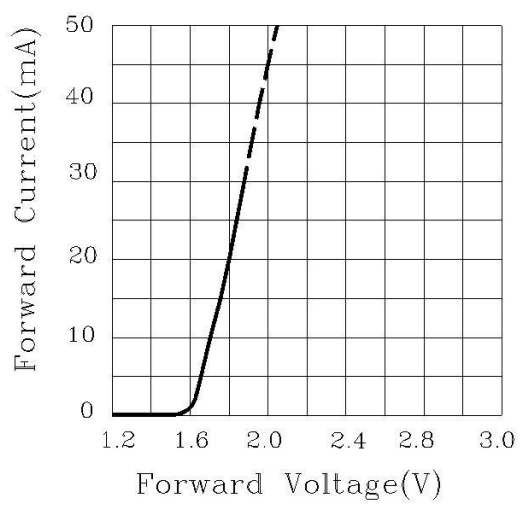


# 0.4 INCH DUAL DIGITS DISPLAY

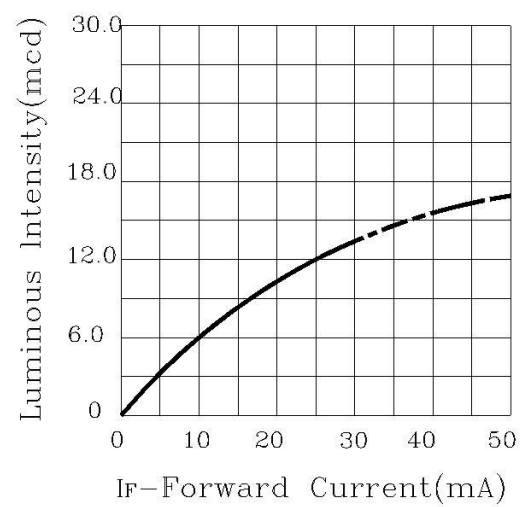
C402I-10

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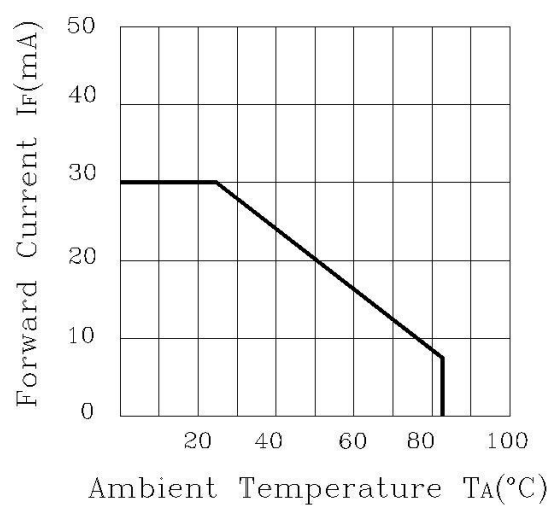
FORWARD CURRENT Vs. FORWARD VOLTAGE



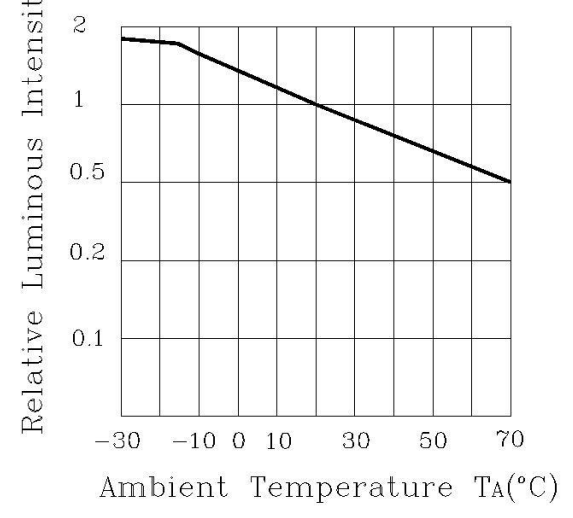
LUMINOUS INTENSITY Vs. FORWARD CURRENT



FORWARD CURRENT DERATING CURVE



LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE





# 0.4 INCH DUAL DIGITS DISPLAY

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## SOLDERING

METHOD	SOLDERING CONDITIONS	REMARK
DIP SOLDERING	Bath temperature: 260 max Immersion time: within 5 sec	Solder no closer than 2mm from the base of the package Using soldering flux," RESIN FLUX" is recommended.
SOLDERING IRON	Soldering iron: 30W or smaller Temperature at tip of iron: 260 or lower Soldering time: within 5 sec.	During soldering, take care not to press the tip of iron against the PIN. (To prevent heat from being transferred directly to the PIN.)

1) When soldering the PIN of Display in a jig that the package is fixed with a panel (See flg.1), be careful not to stress the PIN with iron tip. When soldering Display in a condition that the package is fixed with a panel, be careful not to cling and stress the surface of Display on the panel to avoid damaging the Display.

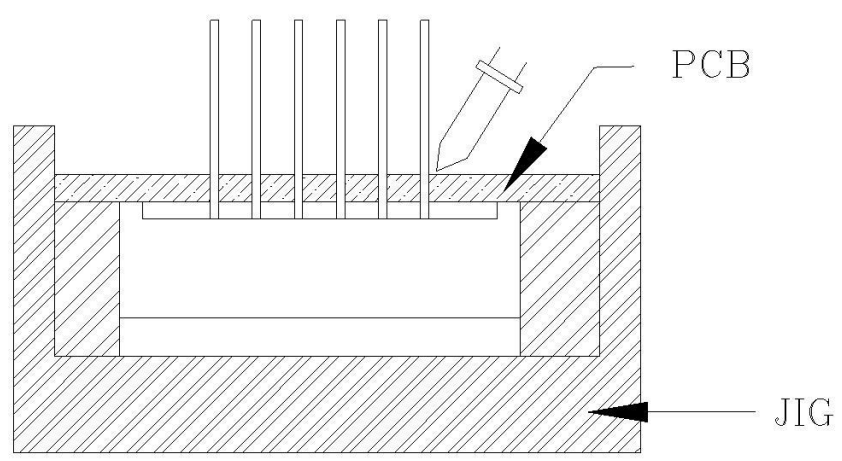


Fig.1

Regarding solution in the tinning oven for product tinning, compound subsolution made of tin & copper and silver is proposed with the temperature of Celsius 260. The proportion of the alloyed solution is tin 95.5: copper 3.5: silver 0.5 by percentage. The time of tinning is constantly 3 seconds.